



Device Material Content

5555 NE Moore Ct.
Hillsboro OR 97124
custreq@lsc.com

Package Code:

FN672

Assembly: ASEM
Size (mm): 27 x 27

Lead pitch (mm): 1.0

MSL: 3

Reflow max (°C): 250

Package: 672 fpBGA
Total Device Weight 3.30 Grams

Products:

LAE3

April, 2018

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	1.48%	0.0489	1.48%	0.0489	Silicon chip	7440-21-3	100.00%	Die size: 8.11 x 8.34 mm
Mold Compound	36.73%	1.2119	1.84%	0.0606	Epoxy Resin	-	5.00%	Mold Compound: Hitachi CEL9750ZHFI0AKL-U (ULA)
			1.84%	0.0606	Phenol Resin	-	5.00%	
			0.07%	0.0024	Carbon Black	1333-86-4	0.20%	
			32.24%	1.0641	Silica	60676-86-0	87.80%	
			0.73%	0.0242	Others	-	2.00%	
D/A Epoxy	0.21%	0.0069	0.17%	0.00550	Silver	7440-22-4	80.00%	Die attach epoxy: Henkel (Ablebond) 2100A
			0.04%	0.00137	Esters & resins	-	20.00%	
Wire	0.60%	0.0198	0.59%	0.0195	Gold (Au)	7440-57-5	98.50%	0.8 mil diameter; 1 wire per solder ball
Solder Balls	19.89%	0.6563	19.19%	0.6333	Tin (Sn)	7440-31-5	96.50%	SAC305
			0.60%	0.0197	Silver (Ag)	7440-22-4	3.00%	
			0.10%	0.0033	Copper (Cu)	7440-50-8	0.50%	
Substrate	41.10%	1.3563	24.25%	0.8002	Laminate*	-	59.00%	BT Resin CCL-HL832NX-A
			5.82%	0.1922	Solder mask PSR4000 AUS 308	-	14.17%	
			9.04%	0.2984	Copper	7440-50-8	22.00%	
			1.66%	0.0549	Nickel plating	7440-02-0	4.05%	
			0.32%	0.0106	Gold plating	7440-57-5	0.78%	

Notes: * 0.24% max. concentration of Bisphenol A (CAS# 80-05-7) in substrate laminate material as impurity - not intentionally added.

The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.

Constituent substances and proportions in epoxy materials are before curing.

The information provided above is representative of the package as of the date listed, and is subject to change at any time.

www.latticesemi.com



PCN#05A-17
Rev. C1